What is claimed is:

1. A component mounter for picking up a component from a component feeder carriage and mounting the component on a board using a transfer head, said component mounter comprising:

(a) a positioner for relatively positioning said board with respect to said transfer head;

(b) a first memory for storing a position measurement result of solder printed on an electrode on said board;

(c) a calculator for calculating mounting coordinates for mounting the component using said transfer head based on said measurement result; and

(d) a controller for driving said positioner based on said mounting coordinates.

2. The component mounter as defined in Claim 1 further comprising a second memory for storing said mounting coordinates.

3. The component mounter as defined in Claim 1, wherein said measurement result is a result of measurement performed by a measuring apparatus installed in the component mounter.

4. The component mounter as defined in Claim 1, wherein said measurement result is a result of measurement performed by a testing function installed in a screen printer for printing solder on the electrode on the board.

5. The component mounter as defined in Claim 1, wherein said position measurement result is a result of measurement performed by a separate appearance inspection device other than the component mounter.

6. A method for picking up a component from a component feeder carriage and mounting the component on a board using a transfer head, said method comprising:

(a) storing a position measurement result of solder printed on an electrode on said board;

(b) calculating mounting coordinates for mounting the component by said transfer head based on said measurement result; and

(c) controlling a positioner for relatively positioning said board with respect to said transfer head based on said mounting coordinates.

7. The method as defined in Claim 6, further comprising:

recognizing a position of said board by a recognition mark on said board; and

obtaining image data for the electrode on said board.

8. The method as defined in Claim 7, further comprising the step of measuring a printing position of solder printed on said electrode as relative coordinates with respect to the recognition mark on said board based on said image data.